

30V P-Channel Power MOSFET

DESCRIPTION

The BLM3401 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.

Application

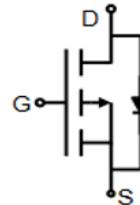
- Power switching application
- Hard switched and High frequency circuits
- Uninterruptible power supply

KEY CHARACTERISTICS

- $V_{DS} = -30V, I_D = -4.2A$
- $R_{DS(ON)} < 55m\Omega @ V_{GS}=-10V$
- $R_{DS(ON)} < 70m\Omega @ V_{GS}=-4.5V$
- $R_{DS(ON)} < 89m\Omega @ V_{GS}=-2.5V$
- High density cell design for lower Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation



SOT-23 Top View



Schematic diagram

Package Marking And Ordering Information

Device Marking	Package	Product Code	Packing
3401	SOT-23	BLM3401	Reel

Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	-4.2	A
Drain Current-Pulsed (Note 1)	I_{DM}	-30	A
Maximum Power Dissipation($T_c=25^\circ C$)	P_D	1.2	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	104	°C/W
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Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-30V, V_{GS}=0V$	-	-	-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA
On Characteristics						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.7	-0.9	-1.3	V
Drain-Source On-State Resistance ^(Note 2)	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-2.1A$	-	45	55	mΩ
		$V_{GS}=-4.5V, I_D=-2.1A$	-	49	70	
		$V_{GS}=-2.5V, I_D=-1A$	-	63	89	
Dynamic Characteristics (Note 3)						
Input Capacitance	C_{iss}	$V_{DS}=-15V, V_{GS}=0V, f=1.0MHz$	-	800	-	pF
Output Capacitance	C_{oss}		-	72	-	pF
Reverse Transfer Capacitance	C_{rss}		-	65	-	pF
Switching Characteristics (Note 3)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-15V, I_D=-3.2A, V_{GS}=-10V, R_{GEN}=6\Omega$	-	7	-	nS
Turn-on Rise Time	t_r		-	3	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	30	-	nS
Turn-Off Fall Time	t_f		-	12	-	nS
Total Gate Charge	Q_g	$V_{DS}=-15V, I_D=-4A$ $V_{GS}=-4.5V$	-	9.5	-	nC
Gate-Source Charge	Q_{gs}		-	2	-	nC
Gate-Drain Charge	Q_{gd}		-	3	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=-1A$	-	-	-1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
3. Guaranteed by design, not subject to production.

Characteristics Curves

Figure 1 Output Characteristics

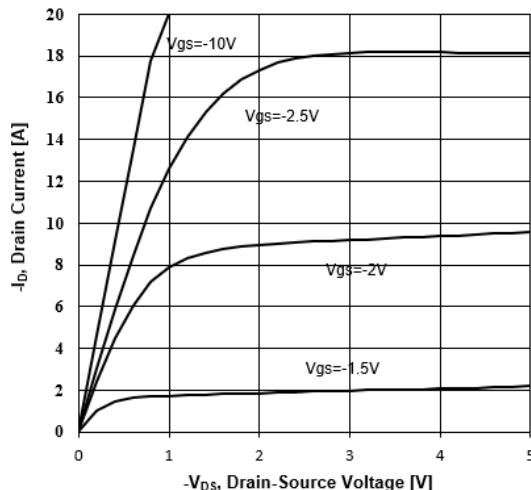


Figure 2 Transfer Characteristics

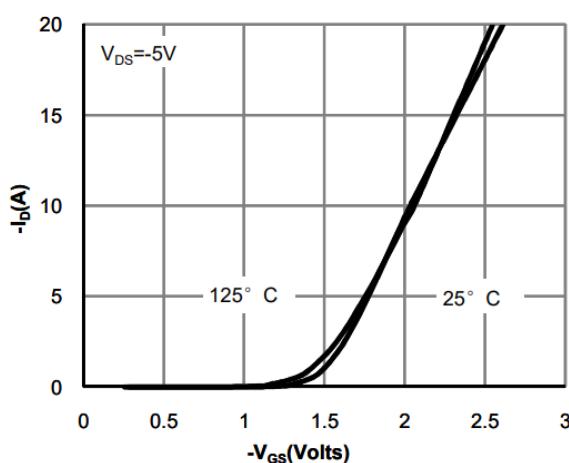
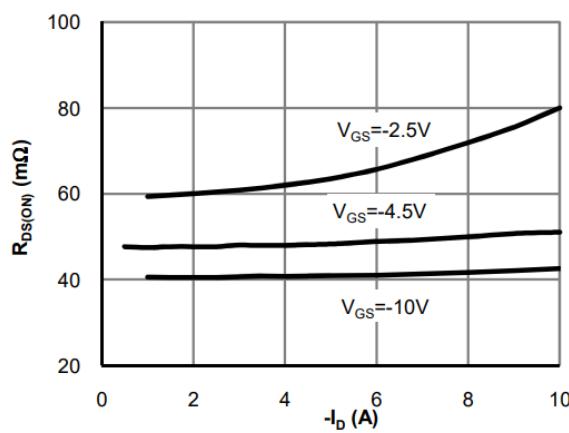

Figure 3 On-Resistance vs. I_D and V_{GS}


Figure 4 On-Resistance vs. Junction Temperature

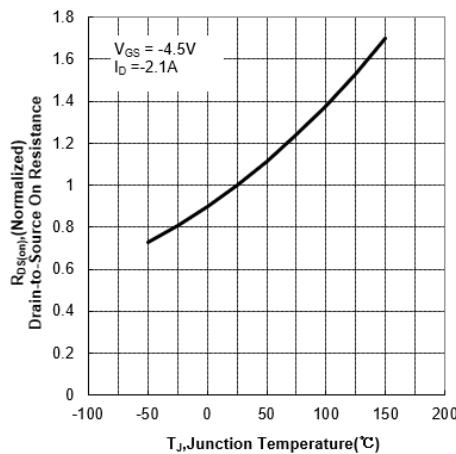
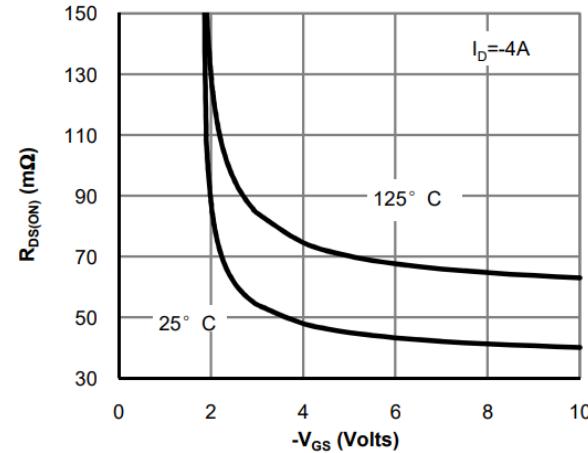

Figure 5 On-Resistance vs. V_{GS}


Figure 6 Body Diode Forward Voltage

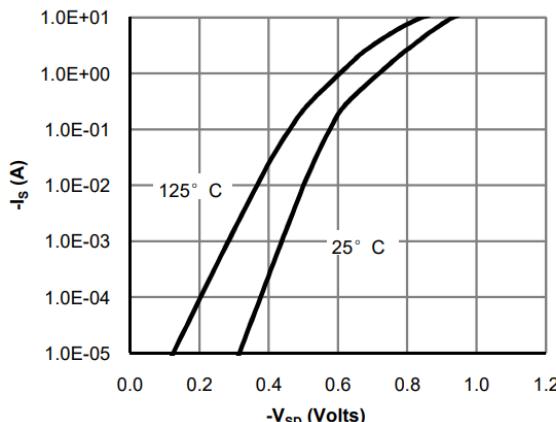


Figure 7 Gate-Charge Characteristics

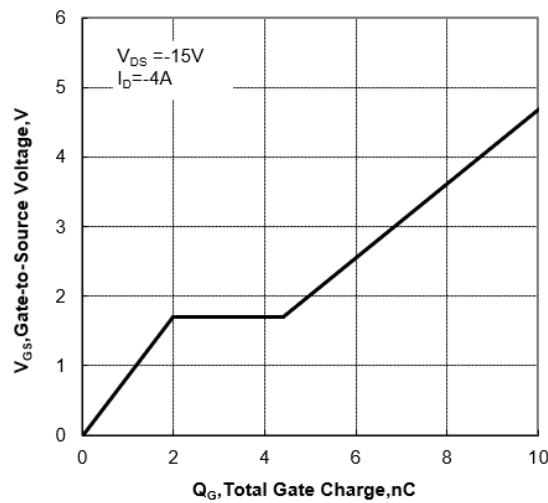


Figure 8 Capacitance Characteristics

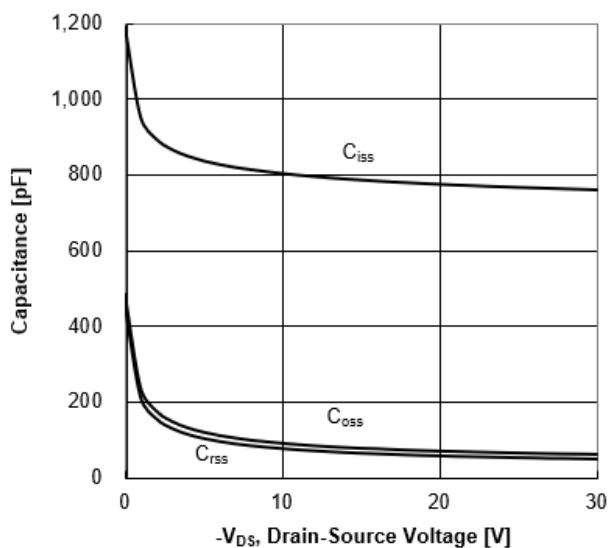


Figure 9 Maximum Forward Biased Safe Operation Area

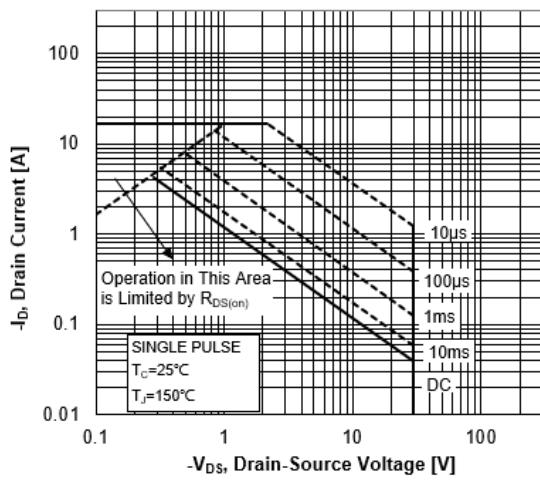


Figure 10 Single Pulse Power Rating Junction-to-Ambient

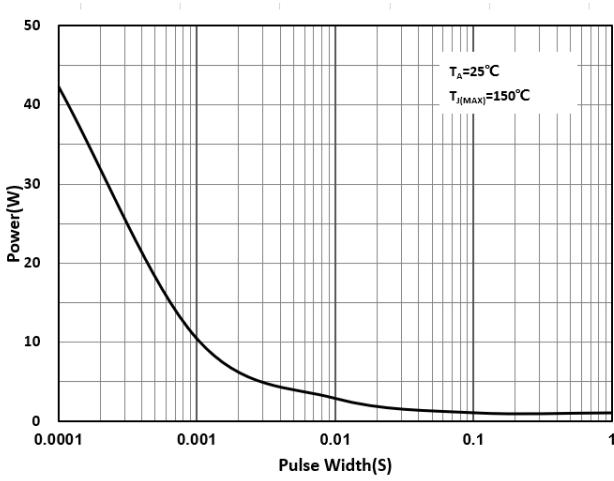
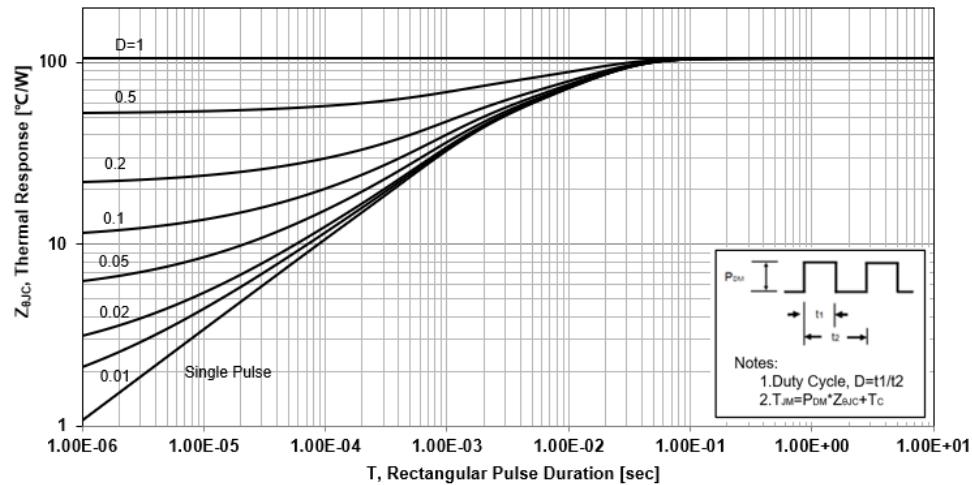


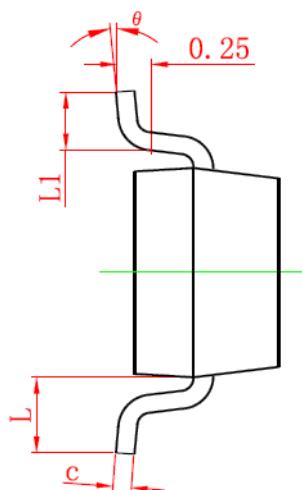
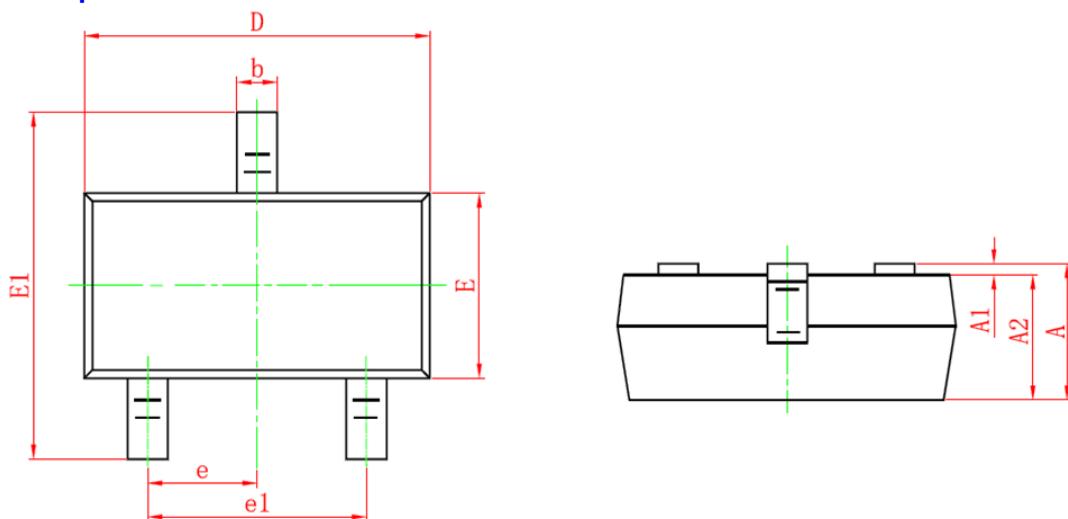
Figure 11 Normalized Maximum Transient Thermal Impedance



Test Circuit and Waveform

Gate Charge Test Circuit	Gate Charge Test Waveform
Resistive Switching Test Circuit	Resistive Switching Test Waveforms
Unclamped Inductive Switching (UIS) Test Circuit	Unclamped Inductive Switching (UIS) Test Waveforms
Diode Recovery Test Circuit	Diode Recovery Test Waveforms

Package Description



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

SOT-23 package

NOTE:

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. Please do not exceed the absolute maximum ratings of the device when circuit designing.
2. When installing the heat sink, please pay attention to the torsional moment and the smoothness of the heat sink.
3. MOSFETs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
4. Shanghai Belling reserves the right to make changes in this specification sheet and is subject to change without prior notice.

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